

Hyperfast Rectifier, 30 A FRED Pt®



PRIMARY CHARACTERISTICS						
I _{F(AV)}	30 A					
V_{R}	650 V					
V _F at I _F	1.4 V					
t _{rr} typ.	33 ns					
T _J max.	175 °C					
Package	2L TO-220AC					
Circuit configuration	Single					

FEATURES

- · Hyper fast and soft recovery
- Low forward voltage drop
- 175 °C operating junction temperature
- · Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC®-JESD 47



RoHS COMPLIANT

HALOGEN FREE Available

 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

Ultra low V_F , soft-switching hyper fast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Repetitive peak reverse voltage	V_{RRM}		650	V		
Average rectified forward current	I _{F(AV)}	T _C = 120 °C	30	^		
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	210	A		
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C		

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	650	-	-		
Forward voltage	V _F	I _F = 30 A	-	1.8	2.1	V	
		I _F = 30 A, T _J = 150 °C	-	1.4	1.6	i	
Develope legicone eviment		V _R = V _R rated	-	0.02	30		
Reverse leakage current I _R		T _J = 150 °C, V _R = V _R rated	-	50	300	μΑ	
Junction capacitance	C _T	V _R = 650 V	-	22	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	t _{rr}	T _J = 25 °C	I _F = 1 A dI _F /dt = 100 A/μs V _R = 30 V	-	37	-	ns	
	trr	T _J = 25 °C		-	33	-	113	
		T _J = 125 °C		- 88 -	-			
Deals received a surrent	$I_{RRM} = \begin{array}{c} T_J = 25 \text{ °C} \\ \hline T_J = 125 \text{ °C} \end{array}$	T _J = 25 °C	I _F = 30 A	=	18	-	۸	
Peak recovery current		$dI_F/dt = 1000 A/\mu s$ $V_R = 400 V$	=	30	-	А		
Daviera management about		T _J = 25 °C		=	450	-	nC	
Reverse recovery charge	Q_{rr}	T _J = 125 °C		=	1350	-	IIC	

THERMAL - MECHANICAL SPECIFICATIONS (T _J = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C	
Thermal resistance, junction to case	R _{thJC}		-	1.0	1.3		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	70	°C/W	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	-	0.5		
Weight			-	2.0	-	g	
vveigni			-	0.07	-	OZ.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style TO-220AC 2L		ETH	3007T		

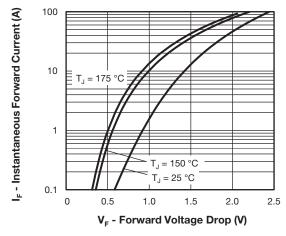


Fig. 1 - Typical Forward Voltage Drop Characteristics

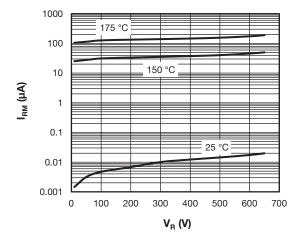


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



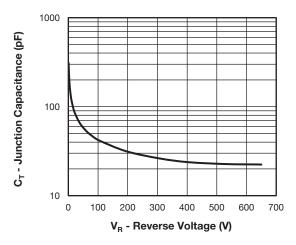


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

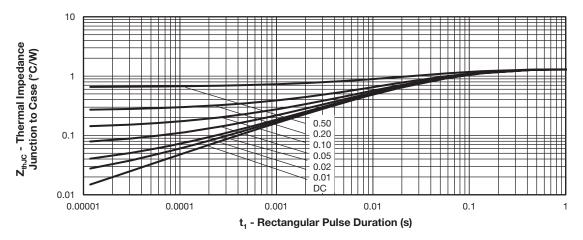


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

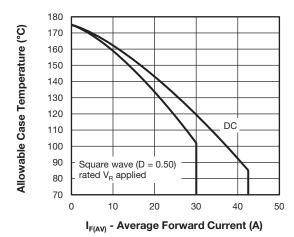


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

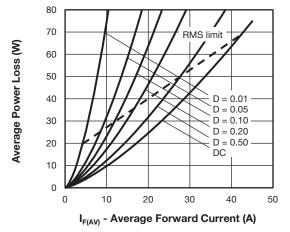


Fig. 6 - Forward Power Loss Characteristics

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; $Pd = forward power loss = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}$; Pd_{REV} = inverse power loss = $V_{R1} \times I_{R} (1 - D)$; I_{R} at V_{R1} = rated V_{R1}

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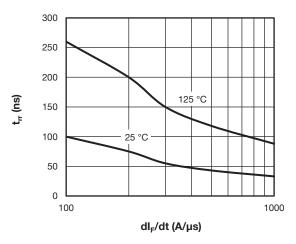


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

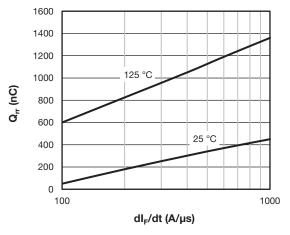
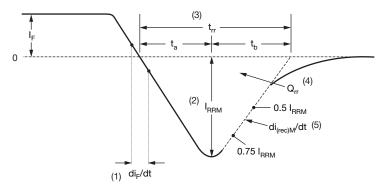


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) ${\rm Q_{rr}}$ area under curve defined by ${\rm t_{rr}}$ and ${\rm I_{RRM}}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

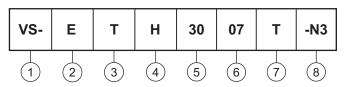
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - E = single diode

3 - Package:

T = TO-220AC

4 - H = hyper fast recovery

5 - Current rating (30 = 30 A)

6 - Voltage rating (07 = 650 V)

7 - True 2 pin TO-220

8 - Environmental digit:

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

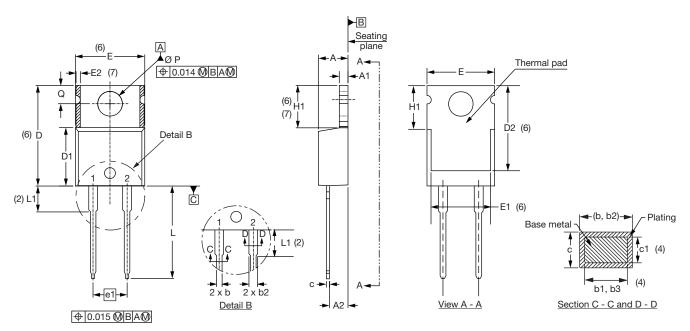
ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-ETH3007T-N3	50	1000	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-220AC 2L	www.vishay.com/doc?96069			
Part marking information	TO-220AC 2L	www.vishay.com/doc?95391			



2L TO-220AC

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INCHES		NOTES	
STIMBOL	MIN.	MAX.	MIN.	MAX.	HOILS	
Α	4.25	4.65	0.167	0.183		
A1	1.14	1.40	0.045	0.055		
A2	2.56	2.92	0.101	0.115		
b	0.69	1.01	0.027	0.040		
b1	0.38	0.97	0.015	0.038	4	
b2	1.20	1.73	0.047	0.068		
b3	1.14	1.73	0.045	0.068	4	
С	0.36	0.61	0.014	0.024		
c1	0.36	0.56	0.014	0.022	4	
D	14.85	15.25	0.585	0.600	3	
D1	8.38	9.02	0.330	0.355		
D2	11.68	12.88	0.460	0.507	6	
Е	10.11	10.51	0.398	0.414	3, 6	

SYMBOL	MILLIMETERS		INCHES		NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except D2, where JEDEC® minimum is 0.480".

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